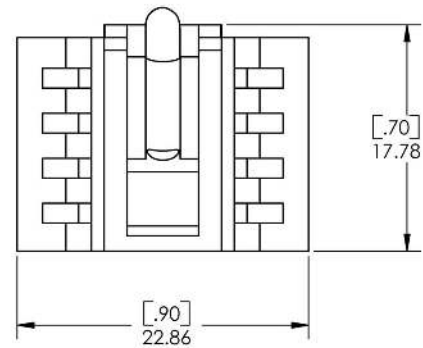
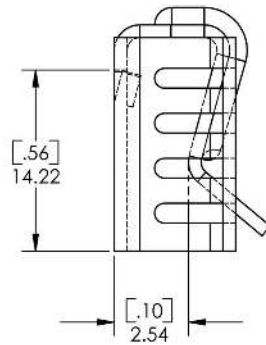
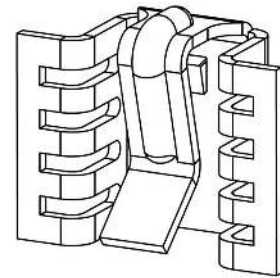
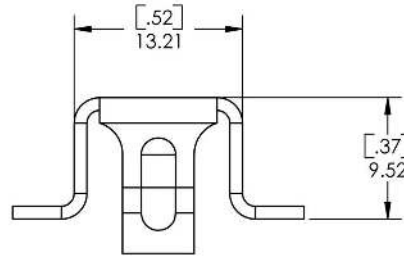


Board Level Heat Sinks



ThermaFlo

P/N: 833502B00000



PRODUCT SPECIFICATIONS

- Devices: TO-220
- Size: 9.5 x 22.8 x 17.8 mm
- Material: Aluminum, 1.0 mm Thick
- Type: Stamped
- IC Mounting: Integrated Spring
- PCB Mounting: Solderable Device Leads
- Finish: Black Anodized
- Package: Bulk

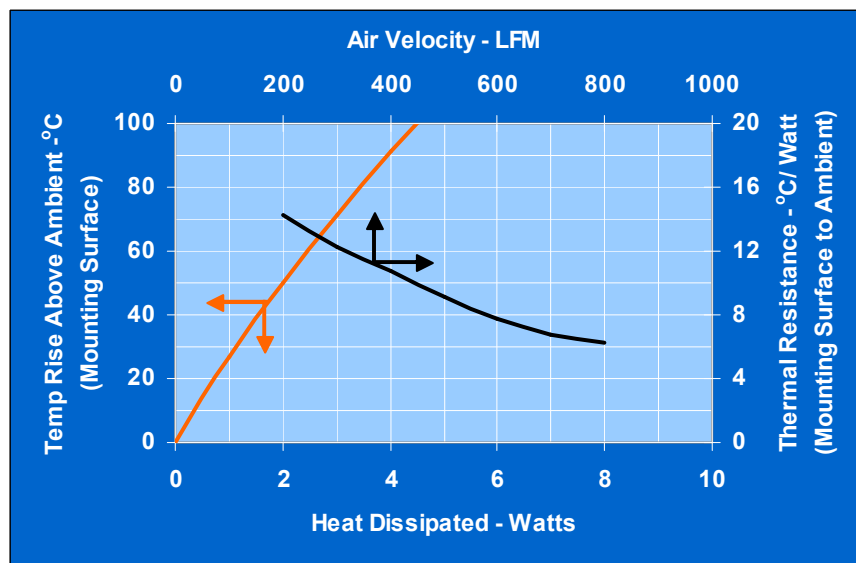
FEATURES & BENEFITS

- No Hardware Device Attachment
- Constant Spring Force Tension
- RoHS Compliant



CUSTOMIZED HEAT SINKS

- Specialized Plating
- Specialized Body Configurations
- Contact Applications Engineering



TO-220

COMAIR ROTRON, INC

8929 Terman Court, San Diego, CA 92121

Ph (858) 348-6200 Fax (858) 566-4577

E-mail: sales@comairrotron.com,

Web: www.comairrotron.com